

L Number	Hits	Search Text	DB	Time stamp
20	206	((zinc with copper) or (metal)) with alloy) and ((dried or drying or dry) with (nitrogen or "N.sub.2") with gas) and ((rinse or rinsing or rinsed) with water) and (electro\$6)	USPAT; US-PGPUB	2003/04/01 17:06
21	1628	(electroplating or electrochemical or electrodeposition or electrolytic) and plating and (((copper with zinc) or metal) with alloy) and (DI or deionized)	USPAT; US-PGPUB	2003/04/01 17:07
22	377	(electroplating or electrochemical or electrodeposition or electrolytic) and plating and (copper with zinc with alloy) and (DI or deionized)	USPAT; US-PGPUB	2003/04/01 17:14
39	22	((electroplating or electrochemical or electrodeposition or electrolytic) and plating and (copper with zinc with alloy) and (DI or deionized)) and metallization	USPAT; US-PGPUB	2003/04/01 17:15
40	239	(electroplating or electrochemical or electrodeposition or electrolytic) and plating and (copper with zinc with alloy) and ((DI or deionized) same (bath or solution or mixed or mixing or dissolve or dissolving))	USPAT; US-PGPUB	2003/04/01 17:17
41	47	((electroplating or electrochemical or electrodeposition or electrolytic) and plating and (copper with zinc with alloy) and ((DI or deionized) same (bath or solution or mixed or mixing or dissolve or dissolving))) and semiconductor	USPAT; US-PGPUB	2003/04/01 17:15
42	125	(electroplating or electrochemical or electrodeposition or electrolytic) and plating and (copper with zinc with alloy) and ((DI or deionized) same (bath or solution or mixed or mixing or dissolve or dissolving) same (salt or sulfate or ion or cation))	USPAT; US-PGPUB	2003/04/01 17:27
-	1	("6515368").PN.	USPAT; US-PGPUB	2003/03/27 16:32
-	284	(205/228).CCLS.	USPAT; US-PGPUB	2003/03/27 16:39
-	78	((205/228).CCLS.) and (copper or zinc or Cu or Zn)	USPAT; US-PGPUB	2003/03/27 16:39
-	74	((205/228).CCLS.) and (copper or zinc or Cu or Zn) and alloy	USPAT; US-PGPUB	2003/03/27 17:01
-	579	(copper same zinc same (alloy or combination)) same (electro\$5 with (plate or plating or solution))	USPAT; US-PGPUB	2003/03/27 17:24
-	128	((copper same zinc same (alloy or combination)) same (electro\$5 with (plate or plating or solution))) and (semiconductor or "IC" or "integrated circuit")	USPAT; US-PGPUB	2003/03/27 17:08
-	344	((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)	USPAT; US-PGPUB	2003/03/27 18:04
-	189	((copper near2 zinc) with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)	USPAT; US-PGPUB	2003/03/27 18:07
-	303	((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution	USPAT; US-PGPUB	2003/03/28 12:27
-	69	((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt)	USPAT; US-PGPUB	2003/03/28 13:07

-	24	(((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt)) and (complexer or complexing)	USPAT; US-PGPUB	2003/03/28 12:29
-	1	("6,176,996").PN.	USPAT; US-PGPUB	2003/03/28 12:29
-	6	("6022808" "6181012" "6197181" "6249055" "6319387" "6368966" "2002/0074234").PN.	USPAT	2003/03/28 12:36
-	0	6515368.URPN.	USPAT	2003/03/28 12:51
-	45	(((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt)) not (((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt)) and (complexer or complexing))	USPAT; US-PGPUB	2003/03/28 13:07
-	234	(((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) not (((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt))	USPAT; US-PGPUB	2003/03/28 14:30
-	23	(((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) not (((((copper with zinc with alloy) or ("Cu Zn")) with ((electro\$7 with (plate or plating or deposition or depositing)) or electroplating)) and solution) and (zinc with salt))) and deionized	USPAT; US-PGPUB	2003/03/28 14:46
-	1	("4356067").PN.	USPAT; US-PGPUB	2003/03/31 11:46
-	5	((deionized or DI) adj water) with (chemical or solution) with bath) and electroplating and ((copper or cu) near2 (zinc or zn))	USPAT; US-PGPUB	2003/03/31 11:53

-	8	((US-6486533-\$ or US-5906725-\$ or US-5388328-\$ or US-5217536-\$ or US-6528424-\$ or US-6515368-\$ or US-6143160-\$ or US-4904354-\$ or US-4686017-\$ or US-4272570-\$ or US-4075066-\$ or US-3919056-\$ or US-3930965-\$ or US-3669854-\$ or US-3716462-\$ or US-6368966-\$ or US-6319387-\$ or US-4036600-\$ or US-4092448-\$ or US-4101386-\$ or US-4049481-\$ or US-6528412-\$ or US-6271589-\$ or US-6251249-\$ or US-4060467-\$ or US-6342146-\$).did. or (US-6235406-\$ or US-6176994-\$ or US-5176812-\$ or US-4465561-\$ or US-4441965-\$ or US-4383898-\$ or US-4379738-\$ or US-4104137-\$ or US-4043878-\$ or US-4859289-\$ or US-4814049-\$ or US-4599279-\$ or US-6197181-\$ or US-5230932-\$ or US-5021269-\$ or US-4730022-\$ or US-4417956-\$ or US-4390377-\$ or US-4356067-\$ or US-4115211-\$ or US-4076600-\$).did. or (US-20020074244-\$ or US-20010014410-\$ or US-20020175419-\$ or US-20020127847-\$ or US-20020134684-\$ or US-20020112965-\$ or US-20030049850-\$ or US-20030010645-\$).did.) and ((DI or deionized) near water)	USPAT; US-PGPUB	2003/03/31 11:50
-	23	((deionized or DI) adj water) same electroplating) and ((copper or cu) near2 (zinc or zn))	USPAT; US-PGPUB	2003/03/31 12:30
-	25	(drying with (gas) same (nitrogen)) and electroplating and rinsing	USPAT; US-PGPUB	2003/03/31 13:08
-	1	("5,441,629").PN.	USPAT; US-PGPUB	2003/03/31 13:18
-	70	(electroplating with bath) same ((DI or deionized) adj water)	USPAT; US-PGPUB	2003/03/31 13:21